ASSOCIATION CONNECTING ELECTRANCE INDUSTRIES® Material Comp © Copyright 2005. I international and Pau	PC. Bannockb	ourn. Illinois. A	Il rights reserved u ntions.	nder both	This docum level parts,	ent is a declaration en	n of the substar compasses all le	ces within the manufacture within the manufacture over level materials for v	urer listed which the 1	item. Note: if nanufacturer	the item is an as has engineering	ssembly with lower responsibility.	
	-21.1 IPC Web Site for Information on IPC-1752 Standard Form http://www.ipc.org/IPC-175x Distribution				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
Supplier Information													
Company name* Con			Company unique ID			Unique ID Authority				Response Date*			
onsemi										2025-05-13			
Contact Name Title - Contact			ontact			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product En			ct Enviro Compliance			NA			Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Rep			Representative			Phone - Representative*			Email -	Email - Representative*			
Product-Env-Stewards Product			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
	1SMB59	1SMB5934BT3G ZEN S		ZEN SMB REG 3W 24V TR		2025-05-13		VN5		114.91	mg	Each	
Manufacturing Proccess Informa	tion												
Terminal Plating / Grid Array M	Plating / Grid Array Material Terminal Base		Alloy J	J-STD-020 MSI	L Rating	Peak Proces	s Body Tempe	ature Max Time at Peal	k Tempera	ture Numb	er of Reflow Cy	cles	
Matte Tin (Sn) - annealed CU Alloy		1	1		260	С	30	secon	nds 3				
Comments													
evel 1 - maximum time at peak temperati	ure during sol	Idering is 10-3	0 seconds										
or more information regarding material	composition	please refer to	o page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	16.81	mg	Supplier	Zinc (Zn)	7440-66-6		0.0202	mg
			Supplier	Iron (Fe)	7439-89-6		0.395	mg
			Supplier	Copper (Cu)	7440-50-8		16.3897	mg
			Supplier	Phosphorus (P)	7723-14-0		0.005	mg
Die	0.7	mg	Supplier	Silicon (Si)	7440-21-3		0.7	mg
Die Attach Solder	0.52	mg	Supplier	Silver (Ag)	7440-22-4		0.013	mg
			А	Lead (Pb)	7439-92-1	7a	0.481	mg
			Supplier	Tin (Sn)	7440-31-5		0.026	mg
Lead Frame	46.99	mg	Supplier	Zinc (Zn)	7440-66-6		0.0564	mg
			Supplier	Iron (Fe)	7439-89-6		1.1043	mg
			Supplier	Copper (Cu)	7440-50-8		45.8153	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0141	mg
Mold Compound-Black	48.07	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		4.807	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2403	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		6.9701	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		31.2455	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		4.807	mg
Plating	1.82	mg	Supplier	Tin (Sn)	7440-31-5		1.82	mg